

# Analog Circuit Design

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## Introduction

This is the material for an intermediate-level MOSFET circuit design course, held at JKU under course number 336.009 (“KV Analoge Schaltungstechnik”).

The course makes heavy use of circuit simulation, using **Xschem** for schematic entry and **ngspice** for simulation. The 130nm CMOS technology **SG13G2** from IHP Microelectronics is used.

Tools and PDK are integrated in the **IIC-OSIC-TOOLS** Docker image, which will be used during the coursework.

### **i** Note

All course material is made publicly available on GitHub and shared under the Apache-2.0 license.

## **IHP's SG13G2 130nm CMOS Technology**

SG13G2 is the name of a 130nm CMOS technology (strictly speaking BiCMOS) from IHP Microelectronics. It features low-voltage (thin-oxide) core MOSFET, high-voltage (thick-oxide) I/O MOSFET, various types of linear resistors, and 7 layers of Aluminium metallization (5 thin plus 2 thick metal layers). This PDK is open-source, and the complete process specification can be found at [SG13G2 process specification](#). While we will not do layouts in this course, the layout rules can be found at [SG13G2 layout rules](#).

For our circuit design, the most important parameters of the available devices are summarized in the following:

- **Low-voltage NMOS:** Device `sg13_1v_nmos`; operating voltage nominal  $V_{DD} = 1.5\text{ V}$ ,  $L_{min} = 0.13\text{ }\mu\text{m}$ ,  $V_{th} \approx 0.5\text{ V}$ ; a triple-well option for the NMOS is available.
- **Low-voltage PMOS:** Device `sg13_1v_pmos`; operating voltage nominal  $V_{DD} = 1.5\text{ V}$ ,  $L_{min} = 0.13\text{ }\mu\text{m}$ ,  $V_{th} \approx -0.47\text{ V}$ .
- **High-voltage NMOS:** Device `sg13_hv_nmos`; operating voltage nominal  $V_{DD} = 3.3\text{ V}$ ,  $L_{min} = 0.45\text{ }\mu\text{m}$ ,  $V_{th} \approx 0.7\text{ V}$ ; a triple-well option for the NMOS is available.
- **High-voltage PMOS:** Device `sg13_hv_pmos`; operating voltage nominal  $V_{DD} = 3.3\text{ V}$ ,  $L_{min} = 0.45\text{ }\mu\text{m}$ ,  $V_{th} \approx -0.65\text{ V}$ .
- **Silicided poly resistor:** Device `rsil`;  $R_{\square} = 7\text{ }\Omega \pm 10\%$ ,  $TC_1 = 3100\text{ ppm/K}$
- **Poly resistor:** Device `rppd`;  $R_{\square} = 260\text{ }\Omega \pm 10\%$ ,  $TC_1 = 170\text{ ppm/K}$
- **Poly resistor high:** Device `rhigh`;  $R_{\square} = 1360\text{ }\Omega \pm 15\%$ ,  $TC_1 = -2300\text{ ppm/K}$
- **MIM capacitor:** Device `cap_cmim`;  $C' = 1.5\text{ fF}/\mu\text{m}^2 \pm 10\%$ ,  $VC_1 = -26\text{ ppm/V}$ ,  $TC_1 = 3.6\text{ ppm/K}$ , breakdown voltage  $> 15\text{ V}$
- **MOM capacitor:** The metal stack is well-suited for MOM capacitors due to 5 thin metal layers, but no primitive capacitor device is available at this point.

## **Schematic Entry Using Xschem**

Xschem is an open-source schematic entry tool with emphasis on integrated circuits. For up-to-date information of the many features of Xschem and the basic operation of it please look at the available [online documentation](#). Usage of Xschem will be learned with the first few basic examples, essentially using a single MOSFET. The usage model of Xschem is that the schematic is hierarchically drawn, and the simulation and evaluation statements are contained in the schematics. Further, Xschem offers embedded graphing, which we will mostly use.

## Circuit Simulation Using ngspice

ngspice is an open-source circuit simulator with SPICE dependency (Nagel 1975). Besides the usual simulated types like **op** (operating point), **dc** (dc sweeps), **tran** (time-domain), or **ac** (small-signal frequency sweeps), ngspice offers a script-like control interface, where many different simulation controls and result evaluations can be done. For detailed information please refer to the latest [online manual](#).

## Integrated IC Design Environment (IIC-OSIC-TOOLS)

In order to make use of the various required components (tools like Xschem and ngspice, PDKs like SG13G2) easier, we will use the **IIC-OSIC-TOOLS**. This is a pre-compiled Docker image which allows to do circuit design on a virtual machine on virtually any type of computing equipment (personal PC, Raspberry Pi, cloud server) on various operating systems (Windows, macOS, Linux). For further information like installed tools, how to setup a VM, etc. please look at [IIC-OSIC-TOOLS GitHub page](#).

### Tip

Please make sure to receive information about your personal VM access ahead of the course start.

Experienced users can install this image on their personal computer, for JKU students the IIC will host a VM on our compute cluster and provide personal login credentials.

### Note

In this course, we assume that students have a basic knowledge of Linux and how to operate it using the terminal. If you are not yet familiar with Linux (which is basically a must when doing integrated circuit design as many tools are only available on Linux), then please check out a Linux introductory course or tutorial online, there are many resources available.

## First Steps

In this first chapter we will learn to use Xschem for schematic entry, and how to operate the ngspice SPICE simulator for circuit simulations. Further, we will make ourselves familiar with the transistor and other passive components available in the IHP Microelectronics SG13G2 technology. While this is strictly speaking a BiCMOS technology offering MOSFETs as well as SiGe HBTs, we will use it as a pure CMOS technology.

## The Metal-Oxide-Semiconductor Field-Effect-Transistor (MOSFET)

In this course, we will not dive into semiconductor physics and derive the device operation bottom-up starting from a fundamental level governed by quantum mechanics. Instead, we will treat the MOSFET as a macroscopic by assuming we have a 4-terminal device, and the performance of this device regarding its terminal voltages and currents we will largely derive from the simulation model.

The circuit symbol that we will use for the n-channel MOSFET is shown in Figure 1, and for the p-channel MOSFET it is shown in Figure 2. A control voltage between gate (“G”) and source (“S”) causes a current to flow between drain (“D”) and source. The MOSFET is a 4-terminal device, so the bulk (“B”) can also control the drain-source current flow. Often, the bulk is connected to source, and then the bulk terminal is not shown to declutter the schematics.

### **i** Note

Strictly speaking is the drain-source current of a MOSFET controlled by the voltage between gate and bulk and the voltage between drain and source. Since bulk is often connected to source anyway, and many circuit designers historically were already familiar with the operation of the bipolar junction transistor, it is common to consider the gate-source voltage (besides the drain-source voltage) as the controlling voltage. This focus on gate-source implies that the source is special compared to the drain. In a typical physical MOSFET, however, the drain and source are constructed exactly the same, and which terminal is drain, and which terminal is source, is only determined by the applied voltage potentials, and can change dynamically during operation (think of a MOSFET operating as a switch... which side is the drain, which side is the source?). Unfortunately, this focus on a “special” source has made its way into some MOSFET compact models. The model that is used in SG13G2 luckily uses the PSP model, which is formulated symmetrically with regards to drain and source, and is thus very well suited for analog and RF circuit design. For a detailed understanding of the PSP model please refer to the [model documentation](#).

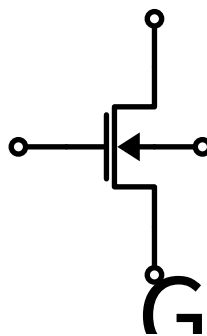


Figure 1: Circuit symbol of n-channel MOSFET.

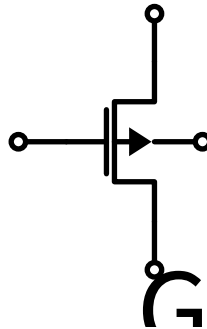
Source: [Article Notebook](#)

Figure 2: Circuit symbol of p-channel MOSFET.

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For hand calculations and theoretical discussions we will use the following simplified large-signal model, shown in Figure 3. A current source  $I_{\text{DS}}$  models the current flow between drain and source, and it is controlled by the three control voltages  $V_{\text{GS}}$ ,  $V_{\text{DS}}$ , and  $V_{\text{SB}}$ . Note that in this way (since  $I_{\text{DS}} = f(V_{\text{DS}})$ ) also a resistive behavior between D and S can be modelled. In case that B and S are shorted then simply  $V_{\text{SB}} = 0$ .

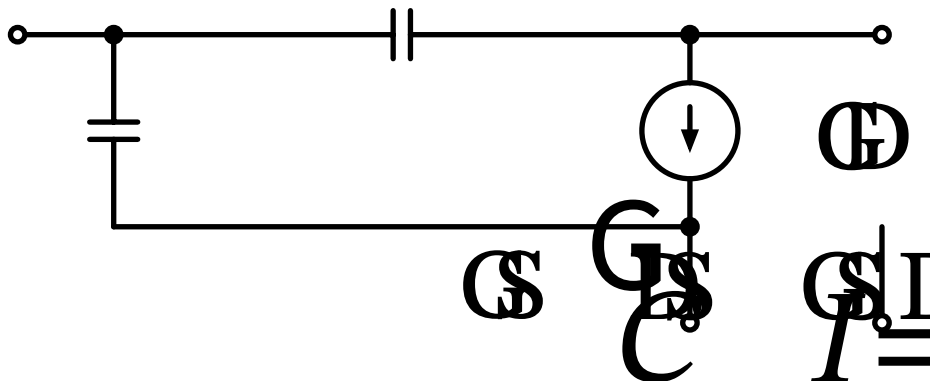
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Figure 3: The MOSFET large-signal model.

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In an ideal MOSFET no dc current is flowing into the gate, the behavior is purely capacitive. We model this by two capacitors:  $C_{\text{GG}} = C_{\text{GS}} + C_{\text{GD}}$  is the total capacitance when looking into the gate of the MOSFET.  $C_{\text{GS}}$  is usually the dominant capacitance, and  $C_{\text{GD}}$  models the capacitive feedback between D and G, usually induced by a topological overlap capacitance

in the physical construction of the MOSFET. This capacitance is often small compared to  $C_{GS}$ , but in situations where we have a large voltage swing at the drain this capacitance will be affected by the [Miller effect](#). In hand calculations we will often set  $C_{GD} = 0$ .

**i** Note

The bulk connection in Figure 3 seems floating as we only consider it a control terminal, where the potential difference between source and bulk influences the behaviour of the MOSFET. However, we do not consider resistive or capacitive effects associated with this node, which is of course a gross simplification, but nevertheless one we will make in this course.

Now, as we are skipping the bottom-up approach of deriving the MOSFET large-signal behaviour from basic principles, we need to understand the behaviour of the elements of the large-signal model in Figure 3 by using a circuit simulator and observing what happens. And generally, a first step in any new IC technology should be to investigate basic MOSFET performance, by doing simple dc sweeps of  $V_{GS}$  and  $V_{DS}$  and looking at  $I_{DS}$  and other large- and small-signal parameters.

As a side note, the students who want to understand MOSFET behaviour from a physical angle should consult the MOSFET chapter from the JKU course “Design of Complex Integrated Circuits” (VL 336.048). A great introduction into MOSFET operation and fabrication is given in (Hu 2010), which is available freely [online](#) and is a recommended read. A very detailed description of the MOSFET (leaving usually no question unanswered) is provided in (Tsividis and McAndrew 2011).

Now, in order to get started, basic Xschem testbenches are prepared, and first simple dc sweeps of various voltages and currents will be done. But before that, please look at the import note below!

**!** Important

Throughout this material, we will stick to the following notations:

- A **dc quantity** is shown with an upper-case letter with upper-case subscripts, like  $V_{GS}$ .
- Double-subscripts denote **dc sources**, like  $V_{DD}$  and  $V_{SS}$ .
- An **ac (small-signal) quantity** is a lower-case letter with a lower-case subscript, like  $g_m$ .
- A **total quantity** (dc plus ac) is shown as a lowercase letter with upper-case subscript, like  $i_{DS}$ .
- A upper-case letter with a lower-case subscript is used to denote **RMS quantities**, like  $I_{ds}$ .

## Large-Signal MOSFET Model

We start with an investigation into the large-signal MOSFET model shown in Figure 3 by using the simple testbench for the LV NMOS shown in Figure 4.

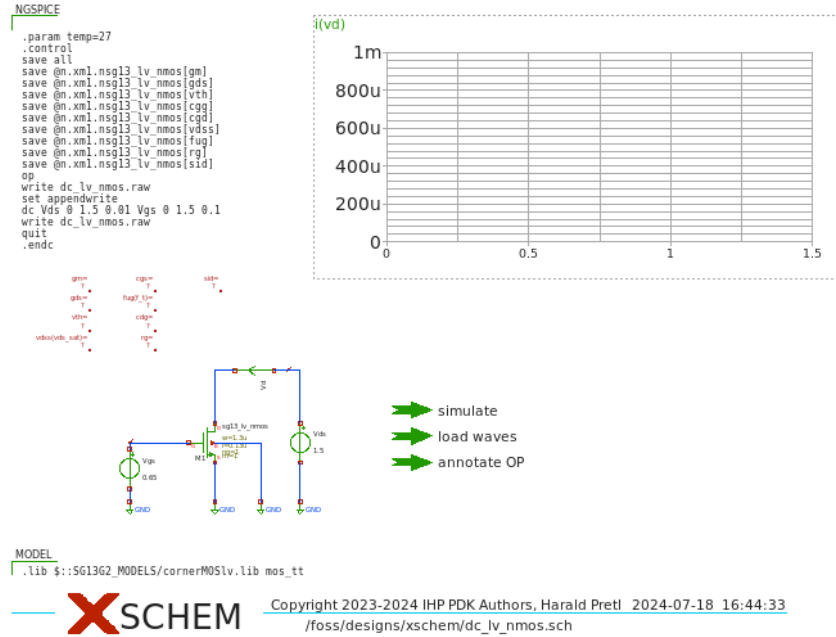


Figure 4: Testbench for NMOS dc sweeps.

### Exercise

Please try to execute the following steps and answer these questions:

1. Get the LV NMOS testbench (available at [https://github.com/iic-jku/analog-circuit-design/blob/main/xschem/dc\\_lv\\_nmos.sch](https://github.com/iic-jku/analog-circuit-design/blob/main/xschem/dc_lv_nmos.sch)) working in your IIC-OSIC-TOOLS environment.
2. Make yourself familiar with Xschem (change the schematic in various ways, run a simulation, graph the result).
3. Make yourself familiar with ngspice (run various simulations, save nets and parameters, use the embedded Xschem graphing, explore the interactive ngspice shell to look at MOSFET model parameters).
4. Explore the LV NMOS `sg13_lv_nmos`:
  1. How is  $I_{DS}$  affected by  $V_{GS}$  and  $V_{DS}$ ?
  2. Change  $W$  and  $L$  of the MOSFET. What is the impact on the above parameters? Can you explain the variations?
  3. When looking at the model parameters in ngspice, you see that there is a  $C_{GD}$  and a  $C_{DG}$ . Why is this, what could be the difference? Sometimes these capacitors show a negative value, why?
5. Build testbenches in Xschem for the LV PMOS, the HV NMOS, and the HV PMOS. Explore the different results.

1. For a given  $W$  and  $L$ , which device provides more drain current? How are the capacitances related?
  2. If you would have to size an inverter, what would be the ideal ratio of  $W_p/W_n$ ? Will you exactly design this ratio, or are the reasons to deviate?
  3. There are LV and HV MOSFETs, and you investigated the difference in performance. What is the rationale when designing circuits for selection either an LV type, and when to choose an HV type?
6. Build a test bench to explore the body effect, start with LV NMOS.
1. What happens when  $V_{BS} \neq 0$ ?

### Small-Signal MOSFET Model

As you have seen in the previous investigations, the large-signal model of Figure 3 describes the behaviour of the MOSFET across a wide range of voltages applied at the MOSFET terminals. Unfortunately, for hand analysis dealing with a nonlinear model is close to impossible, at the very least it is quite tedious.

However, for many practical situations, we bias a MOSFET with a set of dc voltages applied to its terminal, and only apply small signal excursions during operation. If we do this, we can linearize the large-signal model in this dc operating point, and resort to a small-signal model which can be very useful for hand calculations. Many experienced designers analyze their circuits by doing these kind of hand calculations and describing the circuit analytically, which is a great way to understand fundamental performance limits and relationships between parameters.

We will use the small-signal MOSFET model shown in Figure 5 for this course. The current-source  $i_{ds} = g_m v_{gs}$  models the drain current as a function of  $v_{gs}$ , and the resistor  $g_{ds}$  models the dependency of the drain current by  $v_{ds}$ . The drain current dependency on the source-bulk voltage (the so-called “body effect”) is introduced by the current source  $i_{ds} = g_{mb} v_{sb}$ .

Source: [Article Notebook](#)

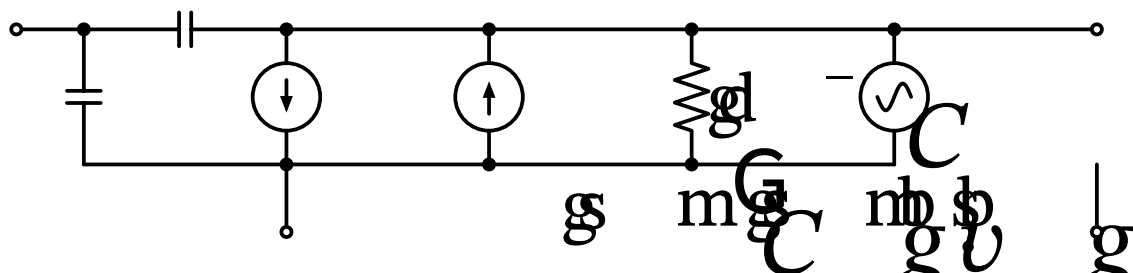


Figure 5: The MOSFET small-signal model.

Source: [Article Notebook](#)



As any electronic device the MOSFET introduces noise into the circuit. In this course we will only consider the drain-source current noise of the MOSFET, given by  $\overline{I_n^2} = 4kT\gamma g_{d0}$  ( $\overline{I_n^2}$  is the power-spectral density of the noise in  $A^2/Hz$ ;  $k$  is the Boltzmann constant;  $T$  is the absolute temperature;  $\gamma$  is a parameter in simplified theory changing between  $\gamma = 2/3$  in saturation and  $\gamma = 1$  for triode operation;  $g_{d0}$  is equal to  $g_m$  in saturation and  $g_{ds}$  in triode).

#### Note

Sometimes we will refer to different operating modes of the MOSFET like “saturation” or “triode”. Generally speaking, when the drain-source voltage is small, then the MOSFET acts as a resistor, and this mode of operation we call “triode” mode. When the drain-source voltage is increased, at some point the drain-source current saturates and is no longer a strong function of the drain-source voltage. This mode is called “saturation” mode. As you can see in the large-signal investigations, these transitions happen gradually, and it is difficult to define a precise point where one operating mode switches to the other one. In this sense we use terms like “triode” and “saturation” only in an approximative sense.

Now we need to see how the small-signal parameters seen in Figure 5 can be investigated and estimated using circuit simulation.

#### Exercise

Please try to execute the following steps and answer the following questions:

1. Reuse the LV NMOS testbench (available at [https://github.com/iic-jku/analog-circuit-design/blob/main/xschem/dc\\_lv\\_nmos.sch](https://github.com/iic-jku/analog-circuit-design/blob/main/xschem/dc_lv_nmos.sch)).
2. Explore the LV NMOS `sg13_lv_nmos`:
  1. How are  $g_m$  and  $g_{ds}$  changing when you change the dc node voltages?
  2. What is the ratio of  $g_m$  to  $g_{mb}$ ? What is the physical reason behind this ratio (you might want to revisit MOSFET device physics at this point)?
  3. Take a look at the device capacitances  $C_{gs}$  and  $C_{gd}$ . Why are they important? What is the relation to  $f_T$ ? *Note:  $f_T$  is the transit frequency where the current gain of the MOSFET drops to 1, and can be approximated by  $2\pi f_T = g_m/C_{gg}$ .*
  4. Look at the drain noise current according to the MOSFET model and compare with a hand calculation of the noise. In the noise equation there is the factor  $\gamma$ , which in triode is  $\gamma = 1$  and in saturation is  $\gamma = 2/3$  according to basic text books. Which value of  $\gamma$  are you calculating? Why might it be different?
3. Go back to your testbench for the LVS PMOS `sg13_lv_pmos`:
  1. What is the difference in  $g_m$ ,  $g_{ds}$ , and other parameters between the NMOS and the PMOS? Why could they be different?

## Conclusion

Congratulations for making it thus far! By now you should have a solid grasp of the tool handling of Xschem and ngspice, and you should be familiar with the large- and small-signal operation of both NMOS and PMOS, and the parameters describing these behaviours. If you feel you are not sufficiently fluent in these things, please go back to the beginning of Section and revisit the relevant sections, or dive into further reading about the MOSFET operation, like in (Hu 2010).

## First Circuit: MOSFET Diode

This sections need to be written, but here is a first figure.

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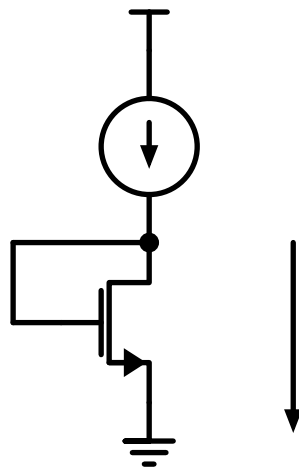


Figure 6: A MOSFET connected as a diode.

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## Transistor Sizing Using $g_m/I_D$ Methodology

When designing circuits it is an important question how to select various parameters of a MOSFET, like  $W$ ,  $L$ , or the bias current  $I_D$ . As a very practical approach we select the  $g_m/I_D$  methodology introduced by P. Jespers and B. Murmann in (Jespers and Murmann 2017). A brief introduction is available [here](#) as well.

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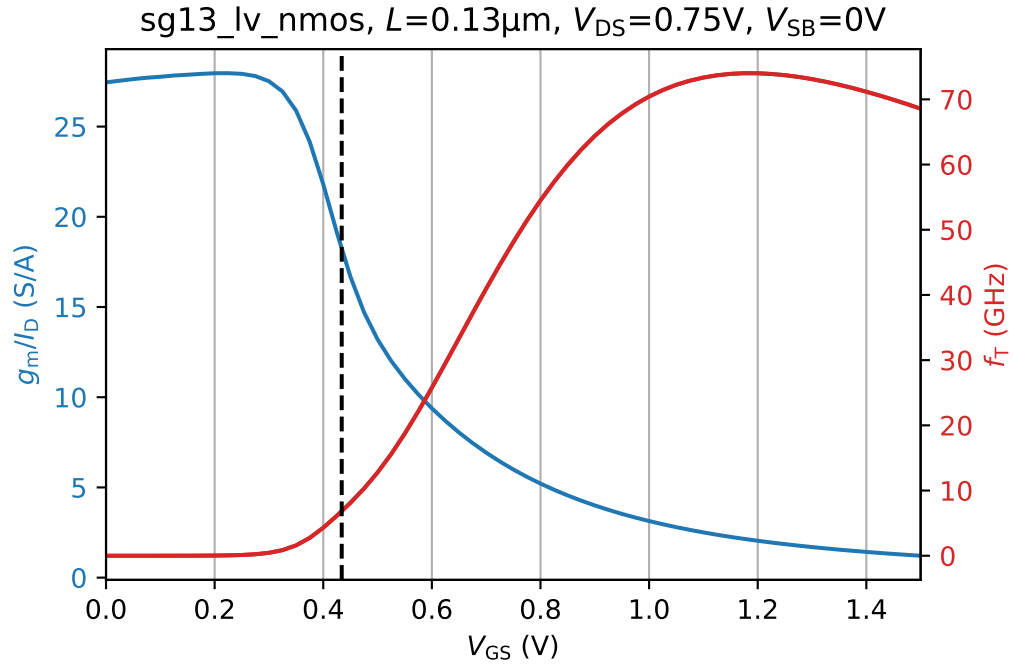


Figure 7: LV NMOS  $g_m/I_D$  vs. transit frequency.

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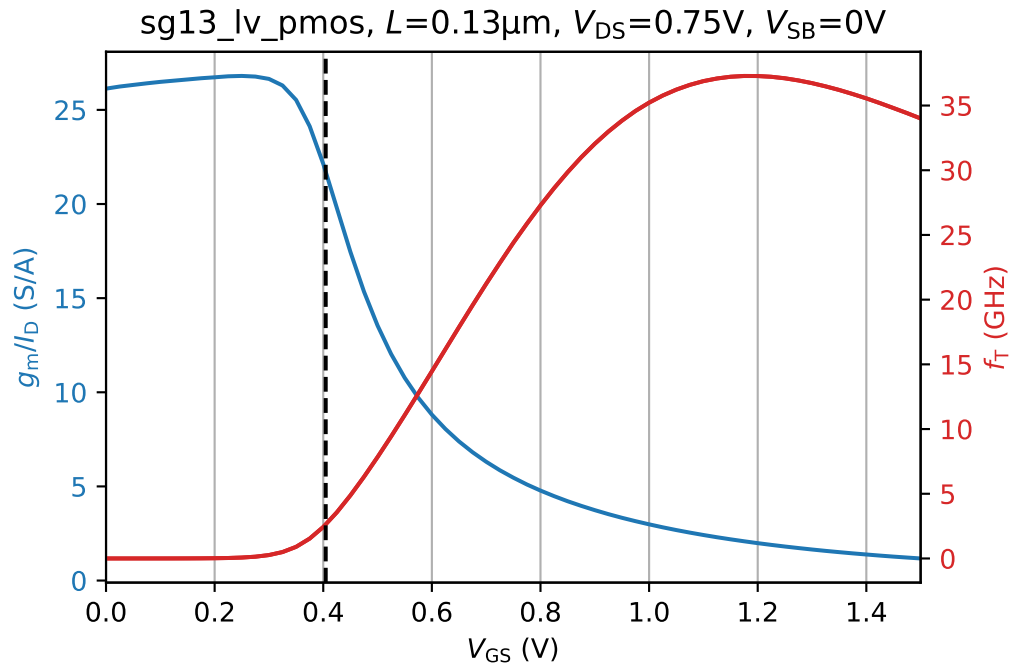


Figure 8: LV PMOS  $g_m/I_D$  vs. transit frequency.

Source: [Article Notebook](#)

**Current Mirror**

**Differential Pair**

**Cascode Stage**

**A Basic 5-Transistor OTA**

**A Fully-Differential OTA**

**Biasing the OTA**

**An RC-OPAMP Filter**

**Summary & Conclusion**

**Appendix: ngspice Cheat Sheet**

**Appendix: Xschem Cheat Sheet**

Source: [Article Notebook](#)

Hu, Chenming. 2010. *Modern Semiconductor Devices for Integrated Circuits*. Pearson.

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